

# **MSN1220S**

# **Preliminary Datasheet**

## N-Channel 20-V (D-S) MOSFET

#### FEATURES

- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

PRODUCTY SUMMARY						
$V_{\text{DS}}$	R	<sub>DS(on)</sub> m(Ω)	I <sub>D</sub> (A)			
20	12	Rdson @4.5V	11.6			
20	15	Rdson @2.5V	10.0			

SOP-8-Single

# Application

- Portable Devices
- Consumer Electronics

#### Mechanical

●Case: SOP-8-Single Package

### **Packing Information**

Package	Packing
SOP-8-Single	3K/13" Reel

Maximum Ratings (T <sub>A</sub> =25°C unless otherwise specified)							
Parameter	Symbol	Limit	Unit				
Drain-Source Voltage	V <sub>DS</sub>	20	V				
Gate-Source Voltage	V <sub>GS</sub>	±12	V				
Continuous Drain Current <sup>1)</sup>	Ι <sub>D</sub>	11.6	А				
Maximum Power Dissipation	P <sub>D</sub>	1.8	W				
Pulsed Drain Current <sup>2)</sup>	I <sub>DM</sub>	46.4	А				
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C				

Typical Thermal Resistance						
Parameter	Symbol	Limit	Unit			
Junction-to-Ambient Thermal Resistance	$R_{ extsf{ heta}JA}$	110	°C/W			

Note:

R0JA is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz. square pad of copper



Electrical Cl	naracteristi	CS (T <sub>A</sub> = 25°C UNLESS OTH	ERWISE	NOTED)		
Characteristics	Symbol	Test Condition	Limits			11 11
Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
		Static				
Drain-Source Breakdown Voltage	B <sub>VDSS</sub>	$VGS = 0V, I_D = 250uA$	20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	VDS=VGS, I <sub>D</sub> =250uA	0.40	0.63	1.00	V
Drain-Source On-State Resistance	D	VGS=4.5V, ID=11.6A	-	10	12	mΩ
	R <sub>DS(on)</sub>	VGS=2.5V, ID=10.0A	-	12	15	mΩ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	VDS=20V, VGS=0V			1.0	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V			±100	nA
		Dynamic <sup>3)</sup>				
Total Gate Charge	Qg		-	16.0	25.60	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =11A, V <sub>GS</sub> =4.5V	-	2.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	4.5	-	nC
Input Capacitance	C <sub>iss</sub>		-	1400	2240	pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1.0MHZ	-	170	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	135	-	pF
	•	• • •				
		Switching				
Turn-On Delay Time	t <sub>d(on)</sub>		-	10	-	ns
Turn-On Rise Time	t <sub>r</sub>	V <sub>DS</sub> =11V, I <sub>D</sub> =1A,	-	13	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =5V,RG=3.3 ଯ	-	28	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	7	-	ns
	•					
	Dra	ain-Source Diode				
Maximum Continuous Body Diode	I <sub>S</sub>	VG=VD=0V , Force Current	-	-	1.2	А
Diode Forward Voltage	V <sub>SD</sub>	IS=1.0A, VGS=0V	-	-	1.5	V

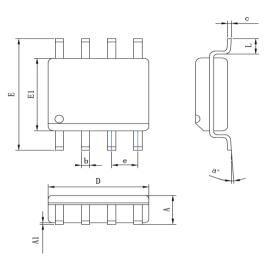
NOTES :

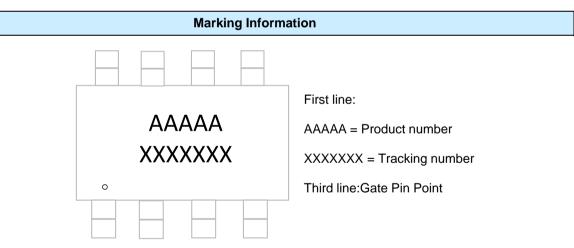
NOTES:
1. Pulse width<300us, Duty cycle<2%.</li>
2. Essentially independent of operating temperature typical characteristics.
3. Repetitive rating, pulse width limited by junction temperature TJ(MAX)=150°C. Ratings are based on low frequency and duty cycles to keep initial TJ =25°C.
4. The maximum current rating is package limited.
5. RQJA is the sum of the junctiontocase and casetoambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch2 with 2oz.square pad of copper.
6. Guaranteed by design. not subject to production testing.



Package Outline Dimensions (inches and millimeters)

SOP-8							
	Dimensions						
SYMBOL	Millimeters		Inches				
	Min	Max	Min	Max			
А	-	1.75		0.069			
A1	0.10	0.23	0.004	0.009			
b	0.35	0.48	0.014	0.019			
С	0.19	0.25	0.007	0.010			
D	4.70	5.10	0.185	0.201			
E	5.80	6.20	0.228	0.244			
E1	3.70	4.10	0.146	0.161			
е	1.27bsc						
L	0.50	0.80	0.020	0.031			
a°	0 °	8 °	0 °	8 °			





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